1762



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No.

09/942,014

Confirmation No. 9002

**Applicant** 

Andrew S. Dewa

Filed

08/29/2001

TC/A.U.

1765

Examiner

Vinh, Lan

Docket No.

A-41588

RECEIVED

Customer No.

23494

SEP 2 2 2003

TC 1700

## **REPLY TO NOTICE OF NON-COMPLIANT AMENDMENT (37 CFR 1.121)**

Commissioner for Patents P.O. Box 1450 Alexandria. VA 22313-1450

MAILING CERTIFICATE	UNDER 37	C.F.R.	§1.8(A
---------------------	----------	--------	--------

I hereby certify that on this date, the above correspondence is being deposited with the US Postal Service as First Class Mail in an envelope addressed to: Non-Fee Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

William B. Kepopler

Date

In response to the Office action of <u>08/19/2003</u>, please add the proper status identifier as follows:

Claim 17 listed below will replace all prior versions. The proper status identifier (currently amended) has been added.

17. (currently amended) The method of claim 11, wherein the attaching step comprises:

A method of fabricating a plurality of hinged structures, comprising:

fabricating a carrier wafer having a plurality of holes therethrough;

mounting a structure wafer to the carrier wafer with alignment relative to the plurality of holes in the carrier wafer;

etching openings through the structure wafer at locations away from the plurality of holes in the carrier wafer, to form a plurality of moveable structures monolithically formed in the structure wafer, where each of the plurality of moveable structures are immobilized by the carrier wafer;

Appl. No. 09/942,014 TI-41588

attaching an actuator to the structure wafer at each location corresponding to one of the plurality of holes in the carrier wafer;

attaching a magnet at a surface of the structure wafer at each of a plurality of locations opposite the locations of the holes in the carrier wafer. and

then removing the carrier wafer from the structure wafer.

Respectfully submitted,

Texas Instruments Incorporated

William B. Kempler

Senior Corporate Patent Counsel

Reg. No. 28,228

Tel.: (972) 917-5452